



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE75242-ESH	Issued	12. August 2021
MA#	MA005595722		
Package	PG-TSDSO-24-21	Weight*	111.99 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	2.76	2.76	27625	27625
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	zinc	7440-66-6	0.063	0.06		565	
	non noble metal	iron	7439-89-6	1.266	1.13		11302	
	non noble metal	copper	7440-50-8	51.392	45.90	47.10	458910	470918
wire	non noble metal	copper	7440-50-8	0.810	0.72	0.72	7235	7235
encapsulation	organic material	carbon black	1333-86-4	0.150	0.13		1344	
	plastics	epoxy resin	-	5.869	5.24		52404	
	inorganic material	silicondioxide	60676-86-0	44.140	39.42	44.79	394153	447901
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25182	25182
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11421	11421
glue	plastics	epoxy resin	-	0.190	0.17		1701	
	noble metal	silver	7440-22-4	0.898	0.80	0.97	8017	9718
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com